CV210-2

Cellular-band Dual-Branch Downconverter

The Communications Edge ™

Product Information

Product Features

- High dynamic range downconverter with integrated LO and IF amplifiers
- Dual channels for diversity
- +29.5 dBm Input IP3
- +12 dBm Input P1dB
- RF: 800 – 925 MHz
- IF: 200 – 250 MHz
- Single supply operation (+5 V)
- 6x6 mm 28-pin QFN package
- Low-side LO configuration
- Common footprint with other PCS/UMTS/cellular versions

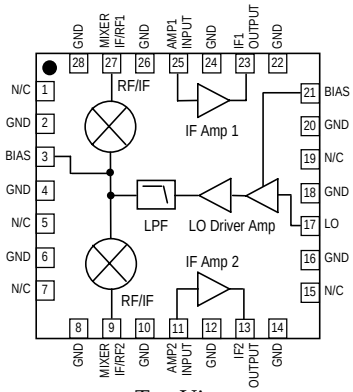
Product Description

The CV210-2 is a dual-channel high-linearity downconverter designed to meet the demanding performance, functionality, and cost goals of current and next generation mobile infrastructure basestations. It provides high dynamic range performance in a low profile surface-mount leadless package that measures 6 x 6 mm square.

It is ideally suited for high dynamic range receiver front ends using diversity receive channels. Functionality includes frequency conversion and IF amplification, while an integrated LO driver amplifier powers the passive mixer. The MCM is implemented with reliable and mature GaAs MESFET and InGaP HBT technology.

Typical applications include frequency downconversion used in CDMA/GSM/TDMA, CDMA2000, and EDGE 2.5G and 3G mobile base transceiver stations.

Functional Diagram



Top View

Specifications[1]

Parameters	Units	Min	Typ	Max	Comments
RF Frequency Range	MHz	800		925	
LO Frequency Range	MHz	550		725	
IF Center Frequency Range	MHz	200	240	250	See note 2
% Bandwidth around IF center frequency	%		±7.5		See note 3
SSB Conversion Gain	dB	8	10	12	Temp = 25° C
Gain Drift over Temp (-40° C to 85° C)	dB	-1.5	±0.3	1.5	Referenced to +25° C
Input IP3	dBm	+25	+29.5		See note 4
Input IP2	dBm	+33	+39		See note 4
Input 1 dB Compression Point	dBm		+12		See note 4
Noise Figure	dB		10.2		See note 5
LO Input Drive Level	dBm	-2.5	0	+2.5	
LO-RF Isolation	dB		18		P_{LO} = 0 dBm
LO-IF Isolation	dB		32		P_{LO} = 0 dBm
Branch-Branch Isolation	dB		45		
Return Loss: RF Port	dB		20		
Return Loss: LO Port	dB		20		
Return Loss: IF Port	dB		12		
Operating Supply Voltage	V		+5		
Supply Current	mA	320	360	475	
Thermal Resistance	°C / W			27	
Junction Temperature	°C			160	See note 6

1. Specifications when using the application specific circuit (shown on page 3) with a low side LO = 0 dBm in a downconverting application at 25° C.
2. IF matching components affect the center IF frequency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications.engineering@wj.com.
3. The IF bandwidth of the converter is defined as 15% around any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around the total ±7.5% bandwidth. ie. with a center frequency of 240 MHz, the specifications are valid from 240 ± 18 MHz.
4. Assumes the supply voltage = +5 V. IIP3 is measured with Δf = 1 MHz with RF_{in} = -5 dBm / tone.
5. Assumes LO injection noise is filtered at the thermal noise floor, -174 dBm/Hz, at the RF, IF, and Image frequencies.
6. The maximum junction temperature ensures a minimum MTBF rating of 1 million hours of usage.

Absolute Maximum Rating

Parameters	Rating
Operating Case Temperature	-40° to +85° C
Storage Temperature	-55° to +125° C
DC Voltage	+5.5 V
Junction Temperature	+220 °C

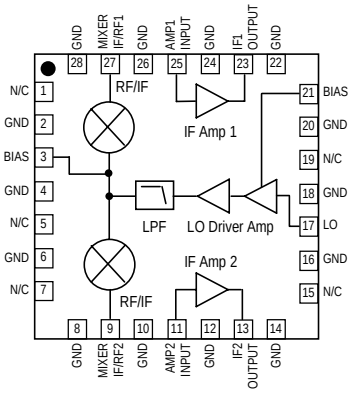
Operation of this device above any of these parameters may cause permanent damage.

Ordering Information

Part No.	Description
CV210-2	Cellular-band Dual-Branch Downconverter
CV210-2PCB240	Fully-Assembled Application Board, IF = 240 MHz

Specifications and information are subject to change without notice

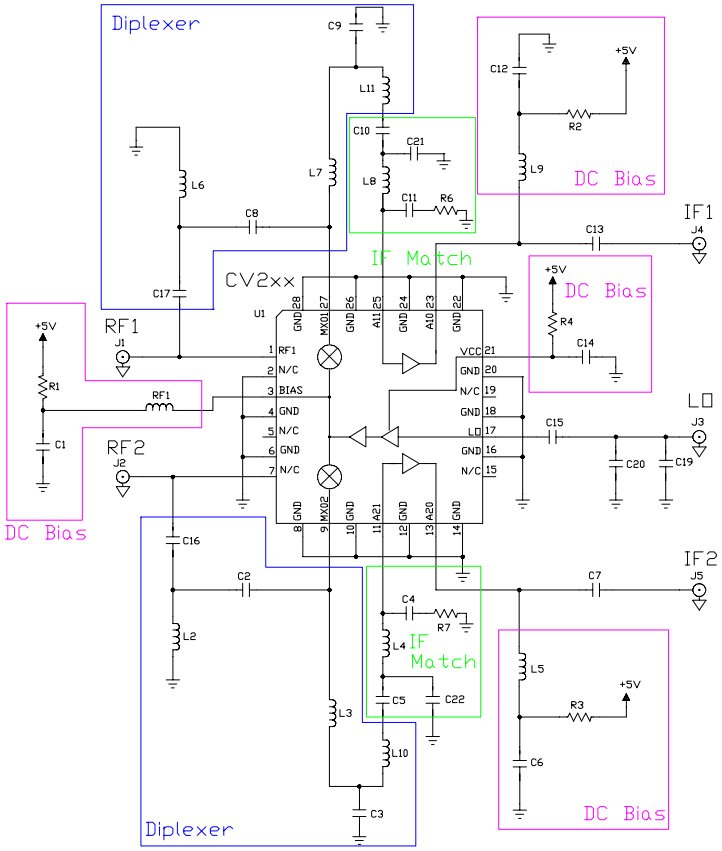
Device Architecture / Application Circuit Information



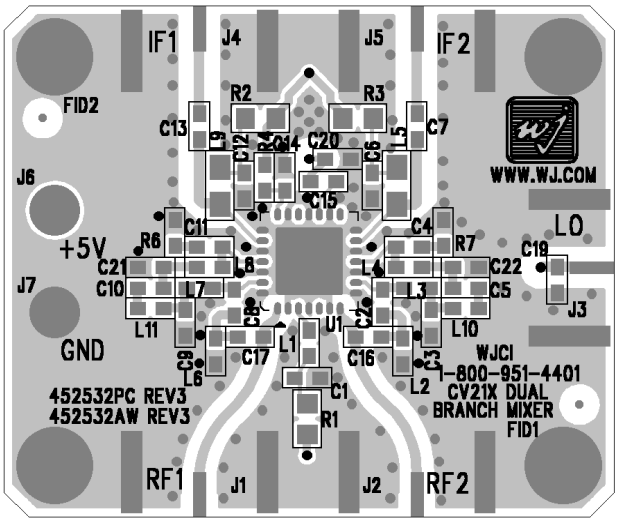
Typical Downconverter Performance Chain Analysis (Each Branch)

Stage	Gain (dB)	Input P1dB (dBm)	Input IP3 (dBm)	NF (dB)	Current (mA)	Cumulative Performance			
						Gain (dB)	Input P1dB (dBm)	Input IP3 (dBm)	NF (dB)
LO Amp / MMIC Mixer	-9	11	30	9.3	60	-9	11	30	9.3
IF Amplifier	19	2	22	1.8	150	10	8	27.5	11
CV210-2	**Cumulative Performance**				**360***	**10**	**+8**	**+27.5**	**11**

* The 2nd branch includes another mixer and IF amplifier, which increases the total current consumption of the MCM to be 360 mA.



Printed Circuit Board Material:
.014" FR-4, 4 layers, .062" total thickness



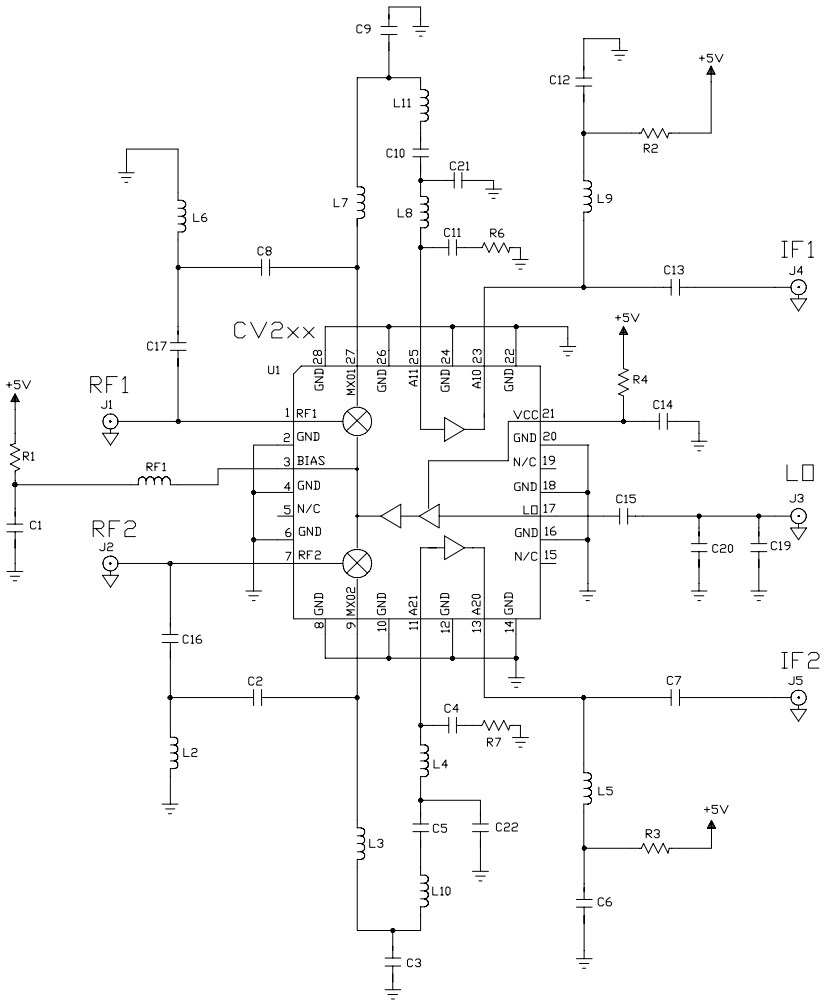
CV210-2: The application circuit can be broken up into three main functions as denoted in the colored dotted areas above: RF/IF diplexing (blue), IF amplifier matching (green), and dc biasing (purple). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ dual-branch converters. Further details are given in the Application Note located on the website titled "CV2xx Series - PWB Design Guidelines".

External Diplexer: In a downconversion application, the incoming RF signal impinges on the switching elements of the mixer; the interaction with these switches produces a signal at the IF frequency. The two signals (RF and IF) are directed to the appropriate ports by the external diplexer. A six-element diplexer is used in the circuit implementation.

IF Amplifier Matching: The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure, is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

DC biasing: DC bias must be provided for the LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

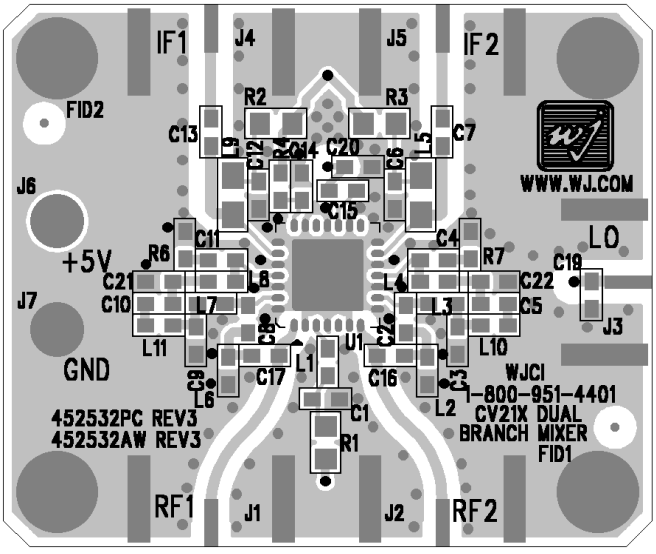
Application Circuit: IF = 240 MHz (CV210-2PCB240)



Bill of Materials

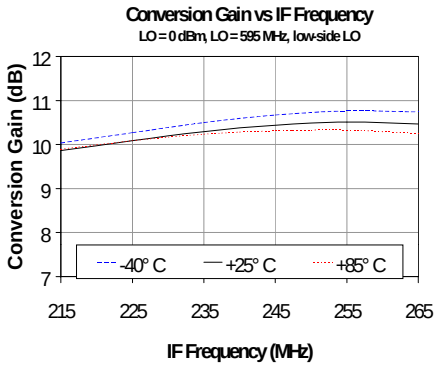
Ref. Desig.	Component	Size
R1	11.3 Ω chip resistor	0805
R2, R3, R4	0 Ω chip resistor	0603
R6, R7	2.2 Ω chip resistor	0603
C1, C5, C10, C15	1000 pF chip capacitor	0603
C2, C8	5.6 pF chip capacitor	0603
C3, C9	12 pF chip capacitor	0603
C4, C11	2 pF chip capacitor	0603
C6, C12, C14	.01 µF chip capacitor	0603
C7, C13	100 pF chip capacitor	0603
L1	120 nH chip inductor	0603
L2, L6	12 nH chip inductor	0603
L3, L7	33 nH chip inductor	0603
L4, L8	56 nH chip inductor	0603
L5, L9	220 nH chip inductor	0805
L10, L11	15 nH chip inductor	0603
C19, C20, C21, C22	Do Not Place	
U1	CV210-2 WJ Converter	QFN

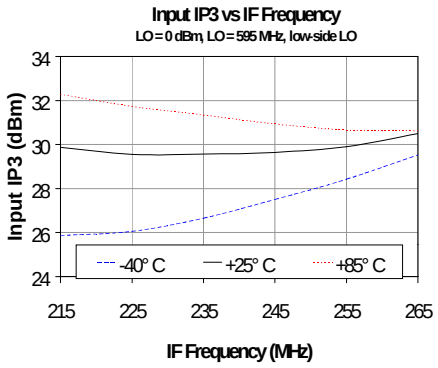
PCB Layout

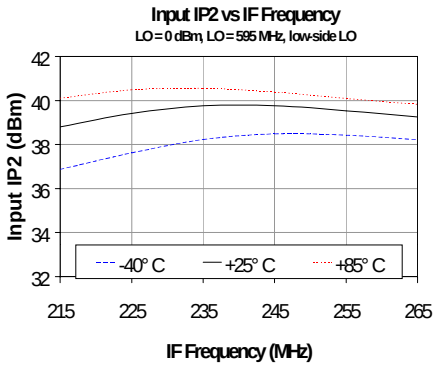


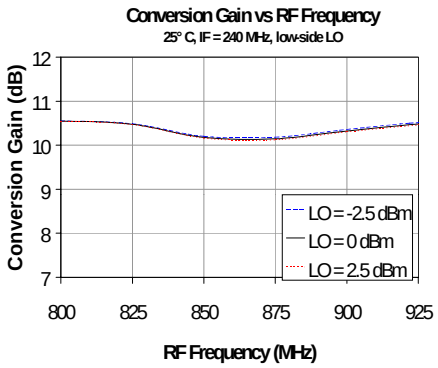
Circuit Board Material: .014” FR-4, 4 layers, .062” total thickness

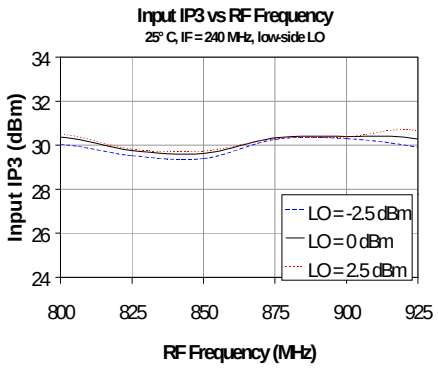
CV210-2PCB240 Application Circuit Performance Plots

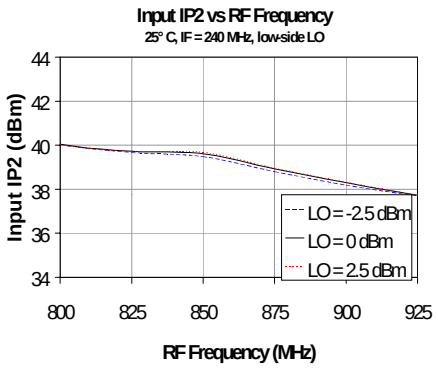


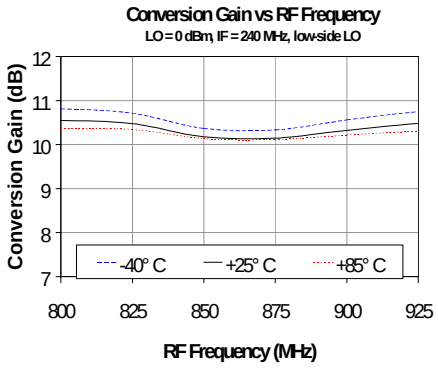


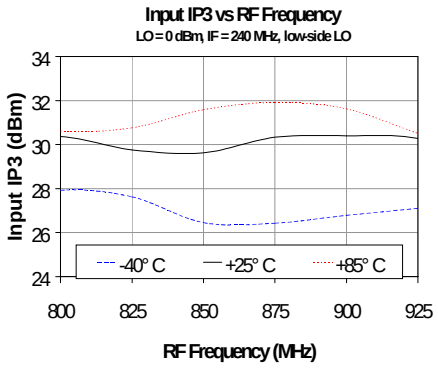


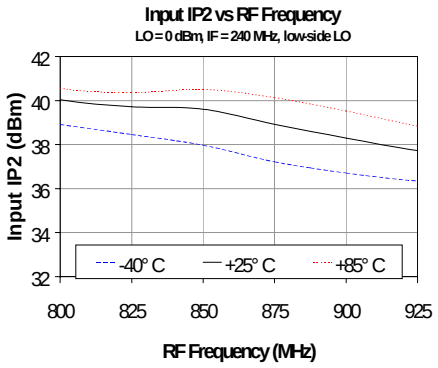


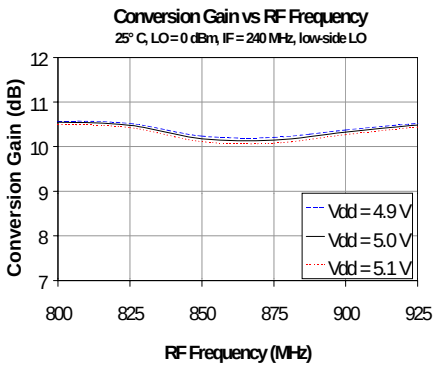


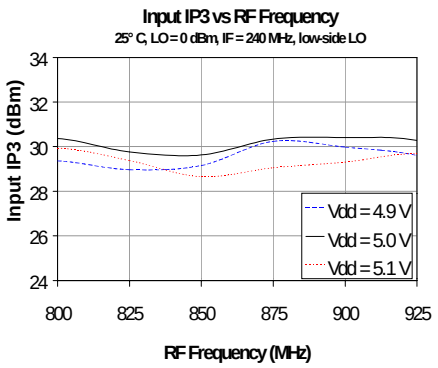


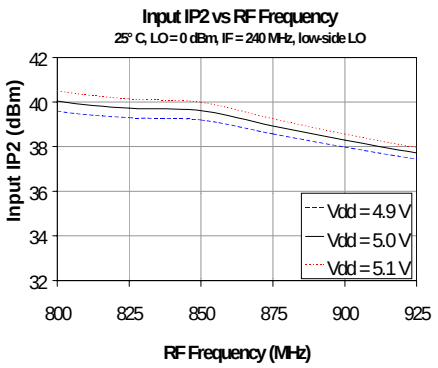




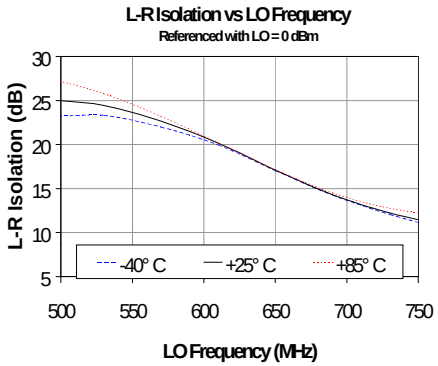


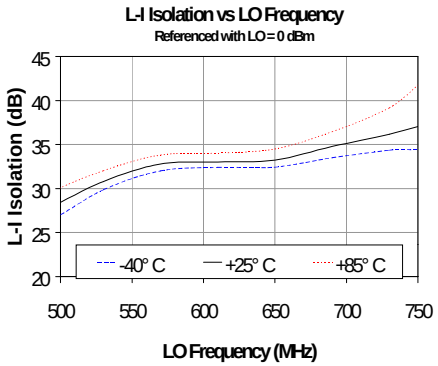


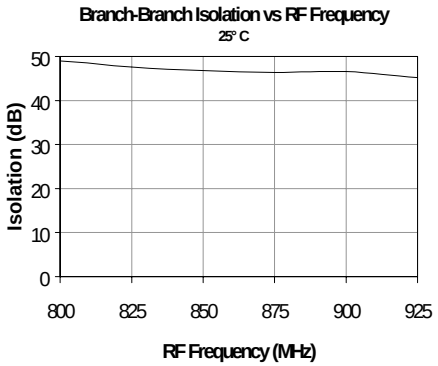


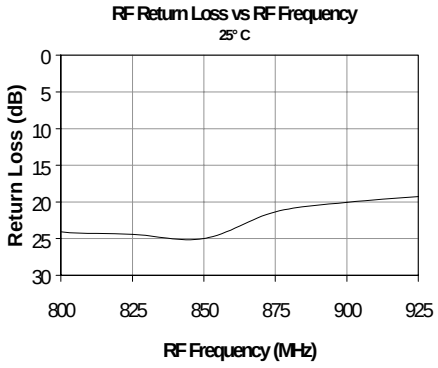


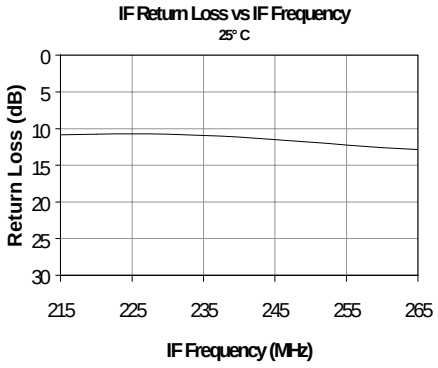
CV210-2PCB240 Application Circuit Performance Plots (cont'd)

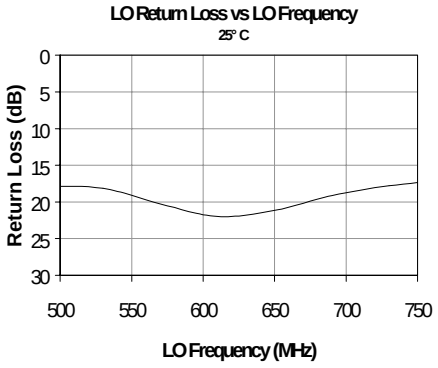


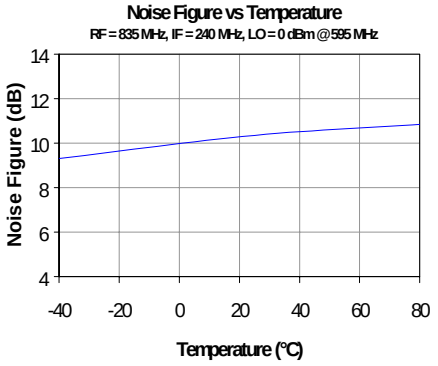


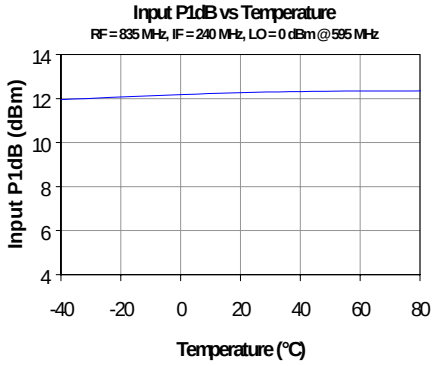












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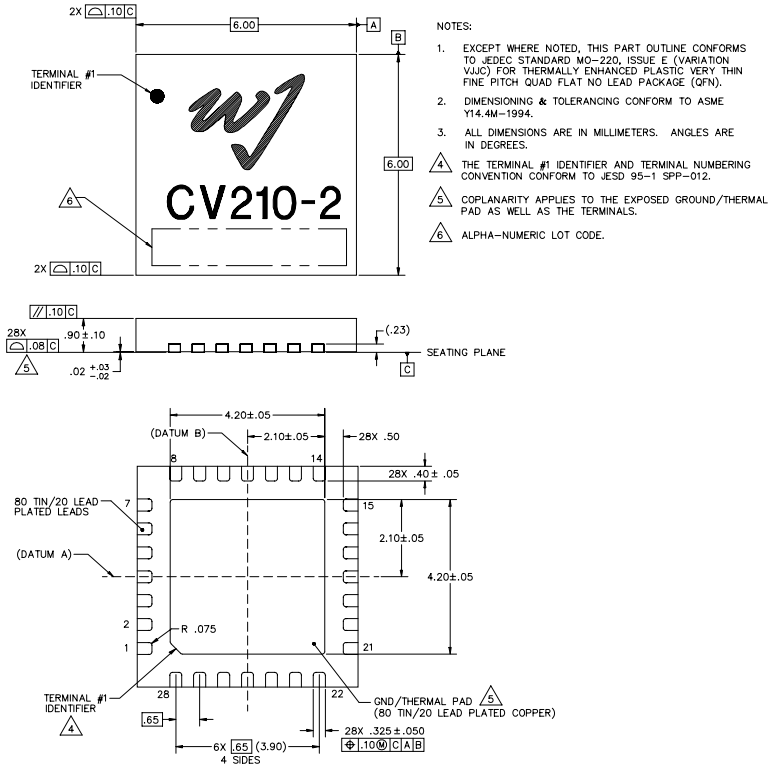
Cellular-band Dual-Branch Downconverter

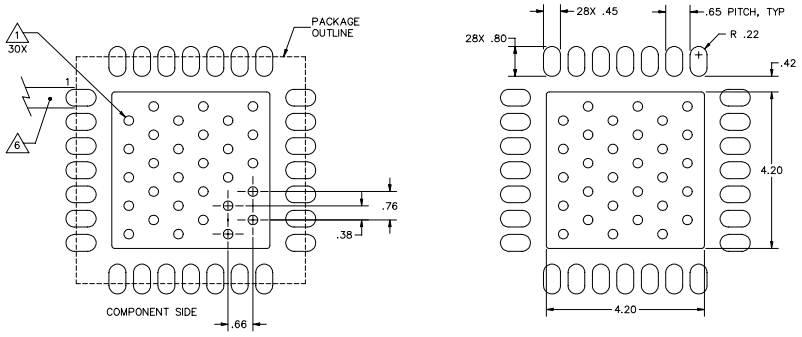
The Communications Edge ™

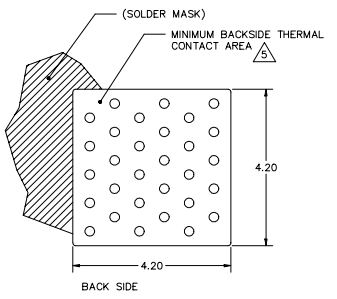
Product Information

Outline Drawing



Mounting Configuration / Land Pattern





NOTES:

1. GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
3. TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
5. DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
6. RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
7. USE 1 OZ. COPPER MINIMUM.
8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Product Marking

The component will be lasermarked with a "CV210-2" product label with a four-digit alphanumeric lot code on the top surface of the package. Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

ESD / MSL Information

Caution! ESD sensitive device.

ESD Classification:	Class 1B
Value:	Passes at 500 V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114
ESD Classification:	Class III
Value:	Passes at 500 V
Test:	Charged Device Model (CDM)
Standard:	JEDEC Standard JESD22-C101
MSL Rating:	Level 1 at +250 °C convection reflow
Standard:	JEDEC Standard J-STD-020B

Functional Pin Layout

Pin	FUNCTION	Pin	FUNCTION
1	No Connect	15	No Connect
2	GND	16	GND
3	LO Amp Bias	17	LO input
4	GND	18	GND
5	No Connect	19	No Connect
6	GND	20	GND
7	No Connect	21	+5 V
8	GND	22	GND
9	Channel 2 Mixer RF Input / IF Output	23	Channel 1 IF Amp Output / Bias
10	GND	24	GND
11	Channel 2 IF Amp Input	25	Channel 1 IF Amp Input
12	GND	26	GND
13	Channel 2 IF Amp Output / Bias	27	Channel 1 Mixer RF Input / IF Output
14	GND	28	GND